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(71) Applicant: 3M INNOVATIVE PROPERTIES COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133–3427 (US).

(72) Inventors: ZENNER, Robert, L., D.; 3M Center, P.O. Box 33427, Saint Paul, MN 55133–3427 (US). GERBER, Joel, A.; 3M Center, P.O. Box 33427, Saint Paul, MN 55133–3427 (US). CHEN, Kevin, Yu; 3M Center, P.O. Box 33427, Saint–Paul, MN 55133–3427 (US).

(74) Agents: MCNUTT, Matthew, B. et al.; 3M Innovative Properties Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133–3427 (US).

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(54) Title: HIGH DENSITY ELECTRONIC PACKAGE

(57) Abstract

The present invention is an ultra–thin circuit package with a thinned electronic device having a thickness of less than about 100 μm; a flexible circuit substrate; and an adhesive layer with a thickness of less than about 25 μm between the electronic device and the circuit substrate. The circuit package is less than about 275 μm thick. In another embodiment, the circuit packages may be stacked on one another and laminated together to create an extremely high–density three–dimensional electronic circuit package.

